300mA LDO Regulator with Enable

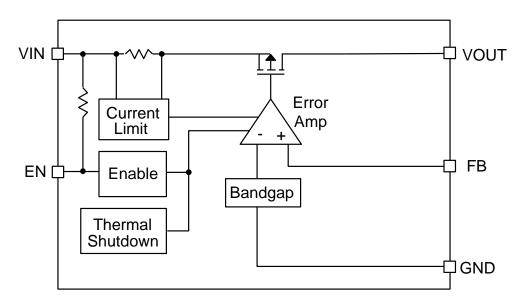
↔ GENERAL DESCRIPTION

The AX6602 is a 300mA, low quiescent, high PSRR, low noise and low dropout linear regulator. The Device includes pass element, error amplifier, band-gap, current limit and thermal shutdown circuitry. The characteristics of low dropout voltage and less quiescent current make it good for some critical current application, for example, some battery powered devices. The typical quiescent current is approximately 90µA. In the shutdown mode, the maximum supply current is less than 1uA. The Output voltage is adjustable from 1.225 to 5.5V. Built-in current-limit, Short current protection and thermal-shutdown functions prevent any fault condition from IC damage.

✤ FEATURES

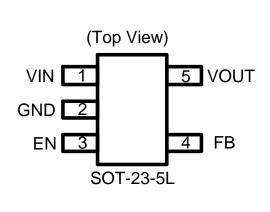
- Input voltage range is up to 6V
- 200mV Dropout at 150mA output current
- Guaranteed 300mA output current
- Low quiescent current 90µA (typ.)
- Adjustable Output voltage form 1.225V to 5.5V
- Maximum shutdown current <1uA
- Fast transient response
- Current limit and thermal shutdown protection
- Short circuit current fold-back
- Available in the 5-Pin Pb-Free SOT-23 Package

*** BLOCK DIAGRAM**



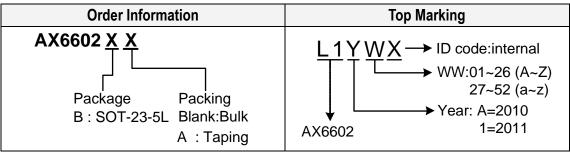
* PIN ASSIGNMENT

The package of AX6602 is SOT-23-5L; the pin assignment is given by:



Name	Description
	-
VIN	Input voltage
GND	Ground
EN	Active-Low Shutdown Input. A logic
	low reduces the supply current to
	less than 1µA. Connect to V _{IN} or
	Floating for normal operation.
	Feedback Input for Setting the
FB	Output Voltage. Connect to an
ГВ	external resistor divider for
	adjustable output operation.
VOUT	Regulator Output Voltage.
1000	Adjustable from 1.225V to +5.5V.

✤ RDER/MARKING INFORMATION



Symbol	Rating	Unit
V _{IN}	GND - 0.3 to + 6.5	V
V _{OUT}	GND - 0.3 to V_{IN} + 0.3	V
V _{EN}	GND - 0.3 to + 6.5	V
V _{FB}	GND - 0.3 to + 6.5	V
PD	400	mW
T _{ST}	-40 to +150	°C
TJ	-40 to +125	°C
θյς	180	°C/W
θ _{JA}	250	°C/W
	V _{IN} V _{OUT} VEN VFB PD T _{ST} T _J θ _{JC}	V _{IN} GND - 0.3 to + 6.5 V _{OUT} GND - 0.3 to V _{IN} + 0.3 V _{EN} GND - 0.3 to V _{IN} + 0.3 V _{EN} GND - 0.3 to + 6.5 V _{FB} GND - 0.3 to + 6.5 PD 400 T _{ST} -40 to +150 T _J -40 to +125 θ _{JC} 180

Note : θ_{JA} is measured with the PCB copper area of approximately 1 in²(Multi-layer).

Characteristics	Symbol	Conditions		Min	Тур	Max	Units
Input Voltage	V _{IN}	(Note1)		2.6	-	6	V
FB Voltage	V_{FB}	VIN=2.6V to 6V, I _{OUT} =1mA		1.2	1.225	1.25	V
FB Input Leakage Current	I _{FB}	V _{FB} =1.225V		-100	-	100	nA
Adjustable Output Voltage Range	Vout			V_{FB}	-	5.5	V
Quiescent Current	ΙQ	I _{OUT} =0mA, V _{IN} =5V		-	90	-	μA
Shutdown Current	I _{SD}	I _{OUT} =0mA, V _{EN} =0V		-	-	1	μA
	V _{DROP}	I _{OUT} =300mA	V _{OUT} =1.50V	-	1.10	1.3	V
			V _{OUT} =1.80V	-	0.8	1.0	
			V _{OUT} =2.50V	-	0.4	0.6	
Dropout Voltage (Note 2)			V _{OUT} =3.00V	-	0.37	0.5	
			V _{OUT} =3.30V	-	0.36	0.5	
			V _{OUT} =4.75V	-	0.25	0.5	
Current Limit (Note 3)	ILIMIT			400	600	-	mA
Short Circuit Current	I _{short}	V _{OUT} <1.0V		-	170	-	mA
Load Regulation (Note 4)	ΔV_{LOAD}	I _{OUT} =10m~300mA		-	-	0.02	%/mA
Dinula Dejection	PSRR		F=120Hz	-	60	-	
Ripple Rejection		С _{ОUT} =2.2uF І _{ОUT} =100mA	F=1KHz	-	55	-	dB
Frankla law of Theorem	V_{ENH}	Regulator Enable		2.0	-	-	N
Enable Input Threshold	V_{ENL}	Regulator Shutdown		-	-	0.8	V
Frabla Dia Ormant	I _{ENH}	V _{EN} =V _{IN}		-	0.003	0.1	
Enable Pin Current	I _{ENL}	V _{EN} =0V		-	0.35	1	μA
Thermal Shutdown	T _{SD}			-	150	-	°C
Thermal Shutdown Hysterics	Т _{SH}			-	30	-	°C

✤ ELECTRICAL CHARACTERISTICS T_A=25°C (unless otherwise noted)

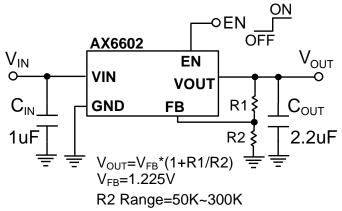
Note 1: Minimum V_{IN} voltage is defined by output adds a dropout voltage.

Note 2: The dropout voltage is defined as (VIN-VOUT), the performance of every AX6602 part, see "Typical Performance Characteristics".

Note 3: Current limit is measured at constant junction temperature by using pulsed testing with a low ON time.

Note 4: Regulation is measured at constant junction temperature by using pulsed testing with a low ON time.

*** APPLICATION CIRCUIT**



***** FUNCTION DESCRIPTIONS

A minimum of 2.2µF capacitor must be connected from V_{OUT} to ground to insure stability. Typically a large storage capacitor is connected from V_{IN} to ground to ensure that the input voltage does not sag below the minimum dropout voltage during the load transient response. This pin must always be dropout voltage higher than V_{OUT} in order for the device to regulate properly.

Enable Function

The AX6602 features an LDO regulator enable/disable function. To assure the LDO regulator will switch on; the EN turn on control level must be greater than 2.0 volts. The LDO regulator will go into the shutdown mode when the voltage on the EN pin falls below 0.8 volts. For to protecting the system, the AX6602 have a quick-discharge function. If the enable function is not needed in a specific application, it may be tied to VIN to keep the LDO regulator in a continuously on state.

FB Function

The output is an adjustable version, the FB voltage is 1.225V. The output voltage can be set by outside resistances. The output voltage, V_{OUT} , is then given by the following equation:

$$V_{OUT} = 1.225 (1 + R1/R2)$$

For the reasons of reducing power dissipation and loop stability, R2 is recommending to choose $50K\sim300K\Omega$.

APPLICATION INFORMATION

Like any low-dropout regulator, the AX6602 requires input and output decoupling capacitors. The device is specifically designed for portable applications requiring minimum board space and smallest components. These capacitors must be correctly selected for good performance (see Capacitor Characteristics Section). Please note that linear regulators with a low dropout voltage have high internal loop gains which require care in guarding against oscillation caused by insufficient decoupling capacitance.

Capacitor Selection

Normally, use a 1µF capacitor on the input and a 2.2µF capacitor on the output of the AX6602. Larger input capacitor values and lower ESR (X5R, X7R) provide better supply-noise rejection and transient response. A higher- value output capacitor (10µF) may be necessary if large, fast transients are anticipated and the device is located several inches from the power source.

Input-Output (Dropout) Voltage

A regulator's minimum input-to-output voltage differential (dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the device uses a PMOS, its dropout voltage is a function of drain-to source on-resistance, $R_{DS (ON)}$, multiplied by the load current:

VDROPOUT = VIN -VOUT = RDS (ON) X IOUT

Current Limit and Short-Circuit Protection

The AX6602 uses a current sense-resistor to monitor the output current. A portion of the PMOS output transistor's current is mirrored to a resistor such that the voltage across this resistor is proportional to the output current. Once the output current exceeds limit threshold, AX6602 would be protected with a limited output current. Further more, when the output is short to ground, the output current would be folded-back to a less limit.

Thermal Considerations

The AX6602 series can deliver a current of up to 300mA over the full operating junction temperature range. However, the maximum output current must be dated at higher ambient temperature to ensure the junction temperature does not exceed 125°C. With all possible conditions, the junction temperature must be within the range specified under operating conditions. Power dissipation can be calculated based on the output current and the voltage drop across regulator.

$$P_D = (V_{IN} - V_{OUT}) I_{OUT}$$

The final operating junction temperature for any set of conditions can be estimated by the following thermal equation:

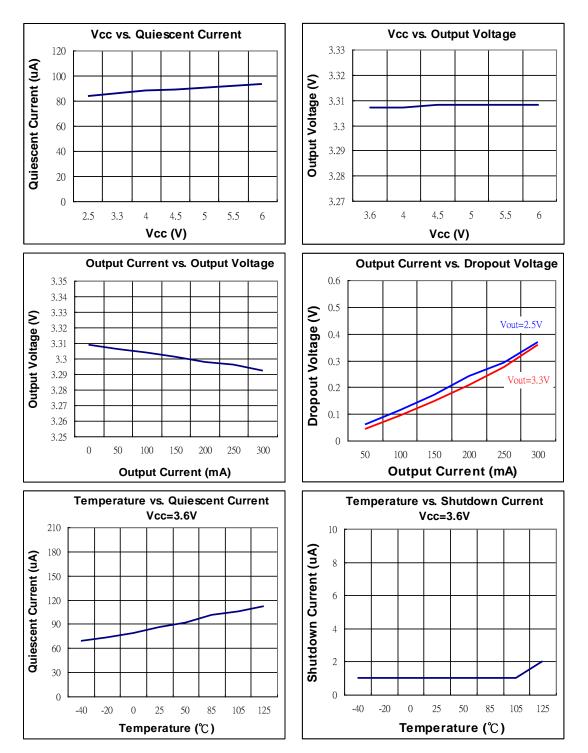
$$P_{D (MAX)} = (T_{J (MAX)} - T_A) / \theta_{JA}$$

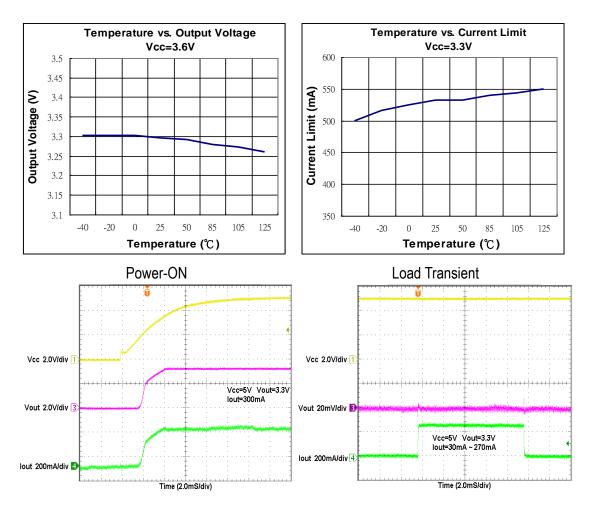
Where $T_{J (MAX)}$ is the maximum junction temperature of the die (125°C) and T_A is the maximum ambient temperature. The junction to ambient thermal resistance (θ_{JA}) for SOT23-5 package at recommended minimum footprint is 250°C/W. Visit our website in which "Recommended Footprints for Soldering Surface Mount Packages" for detail.

PCB Layout

An input capacitance of \cong 1µF is required between the AX6602 input pin and ground (the amount of the capacitance may be increased without limit), this capacitor must be located a distance of not more than 1cm from the input and return to a clean analog ground. Input capacitor can filter out the input voltage spike caused by the surge current due to the inductive effect of the package pin and the printed circuit board's routing wire. Otherwise, the actual voltage at the IN pin may exceed the absolute maximum rating. The output capacitor also must be located a distance of not more than 1cm from output to a clean analog ground. Because it can filter out the output spike caused by the surge current due to the inductive effect of the package pin and the printed circuit board's routing wire.

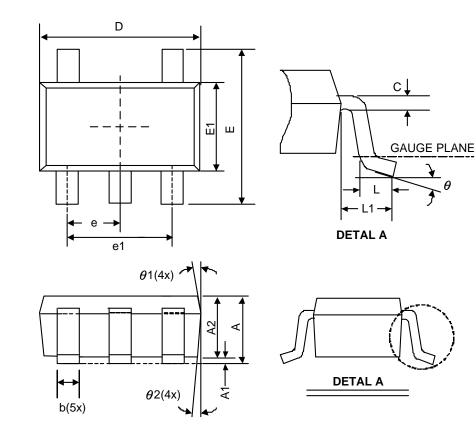
*** TYPICAL CHARACTERISTICS**





*** TYPICAL CHARACTERISTICS (CONTINUOUS)**

*** PACKAGE OUTLINES**



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.45	-	-	0.057
A1	0	0.08	0.15	0	0.003	0.006
A2	0.9	1.1	1.3	0.035	0.043	0.051
b	0.3	0.4	0.5	0.012	0.016	0.02
С	0.08	0.15	0.22	0.003	0.006	0.009
D	2.7	2.9	3.1	0.106	0.114	0.122
E1	1.4	1.6	1.8	0.055	0.063	0.071
E	2.6	2.8	3	0.102	0.11	0.118
L	0.3	0.45	0.6	0.012	0.018	0.024
L1	0.5	0.6	0.7	0.02	0.024	0.028
e1		1.9 BSC		0.075 BSC		
е	0.95 BSC				0.037 BSC	
θ	0°	4°	8º	0°	4 °	8º
<i>θ</i> 1	5°	10°	15°	5°	10°	15°
θ2	5°	10°	15°	5°	10º	15°

JEDEC outline: MO-178 AA